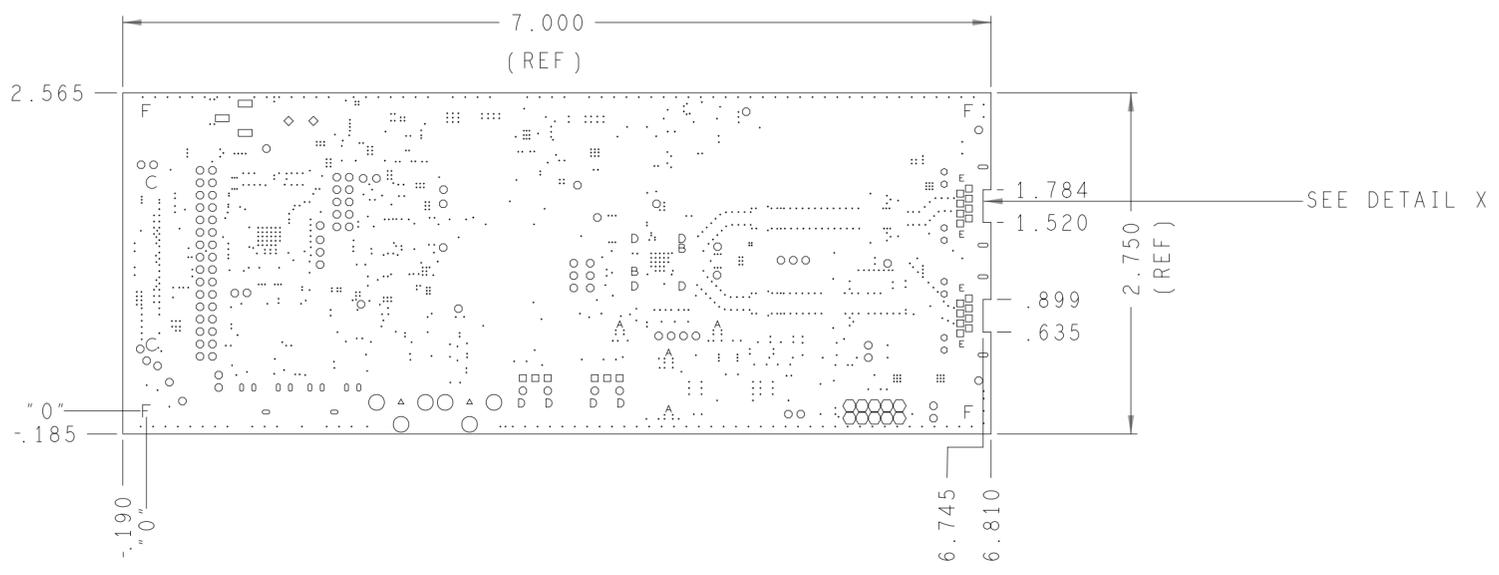
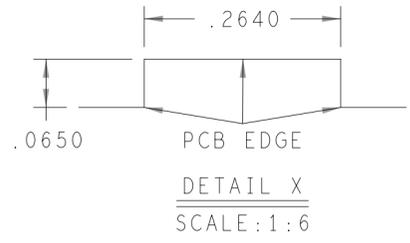


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	15APR22	R. WHITNEY
B	CHANGES AS PER ECR-109621	04OCT22	R. WHITNEY
C	CHANGES AS PER ECR-111941	27JAN23	R. WHITNEY
D	CHANGES AS PER ECR-113566	11APR23	R. WHITNEY
E	CHANGES AS PER ECR-115079	08AUG23	R. WHITNEY

HOLE TOLERANCE
 UNLESS SPECIFIED
 PLATED: +/-3MILS
 NON PLATED: +/-2MILS

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
.	10.0	PLATED	1141	DIA MAX
□	35.0	PLATED	22	
○	40.0	PLATED	10	
◦	43.0	PLATED	8	
◦	45.0	PLATED	97	
◊	55.0	PLATED	2	
△	67.0	PLATED	2	
▢	75.0	PLATED	3	
○	105.0	PLATED	6	
A	20.0	NON-PLATED	4	
B	33.0	NON-PLATED	2	+2/-0
C	35.0	NON-PLATED	2	
D	67.0	NON-PLATED	8	
E	71.0	NON-PLATED	4	
F	125.0	NON-PLATED	4	
◦	59.0x31.0	PLATED	8	
◦	59.0x31.0	PLATED	2	
◦	79.0x31.0	PLATED	4	



PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS .XX -- .010 .XXX -- .005 .XXXX -- .0050 FRACTIONS -- 1/32 ANGLES -- 2	APPROVAL	DATE	GLOBAL OPERATIONS & TECHNOLOGY 1 ANALOG WAY WILMINGTON, MA 01887	
	TEMPLATE ENGINEER	03NOV21		
MATERIAL	HARDWARE SERVICES M. VALE	03NOV21	TITLE FABRICATION EVAL-AD2437A1MZ_BRD CUSTOMER EVALUATION Z	
	HARDWARE SYSTEMS			
	TEST ENGINEER			
FINISH	COMPONENT ENGINEER M. YAN	03NOV21	SIZE C 24355	
	TEST PROCESS			DRAWING NUMBER 09-067221
	HARDWARE RELEASE K. JABATAN	03NOV21		
DESIGNER R. PLANADA	15APR22	REV E		
PTD ENGINEER R. WHITNEY	15APR22			
CHECKER				
DO NOT SCALE DWG		SCALE 1/1	SHEET 1 OF 2	

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SPECIFICATIONS:

ROHS COMPLIANCE NOTE: HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLIANT THE EU RoHS DIRECTIVE 2002/95/EC

MATERIALS: ALL LAMINATES AND BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103, MINIMUM Tg>170degC, Td>300degC, U.L. RATING OF 94 V-0

MATERIAL FAMILY: ISOLA 370HR OR S1000-2 OR IT180 OR EQUIVALENT

CLADDING: EXTERNAL LAYERS .5 OZ. COPPER, OVERPLATE TO 1.5 OZ. INTERNAL SIGNAL LAYERS .5 OZ. COPPER. INTERNAL PLANE LAYERS 1 OZ. COPPER.

NOTE: IF THE LAYER STACKUP CONFLICTS WITH THE ABOVE CLADDING SPECIFICATIONS THEN THE LAYER STACKUP SHALL TAKE PRECEDENCE.

SOLDER MASK: SHALL BE LIQUID PHOTOIMAGEABLE (LPI) APPLIED ON BOTH SIDES OVER BARE COPPER OR GOLD AND SHALL MEET IPC-SM-840 (LATEST REV.) CLASS 3. COLOR GREEN.

SILK SCREEN: SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK, COLOR: WHITE SYNTHETIC INKJET PRINTING ALLOWED FOR DENSE BOARDS, COLOR: WHITE

SURFACE FINISH: ENIG (ELECTROLESS NICKEL/IMMERSION GOLD) PER IPC-4552 LATEST REVISION

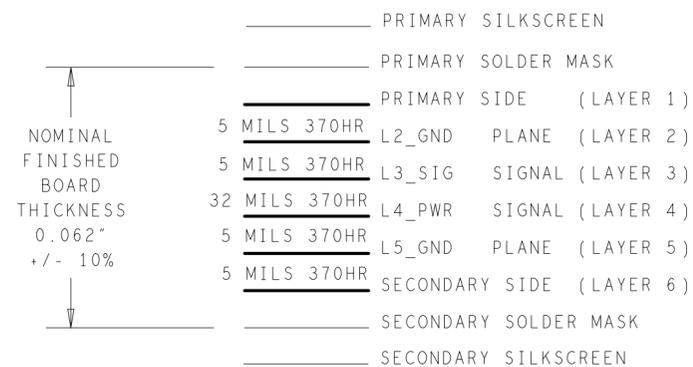
INTENTIONAL SHORTS: IF SUPPLIED DATA INCLUDES A FILE "READ_ME.2", THEN INTENTIONAL NET SHORTS EXIST. CUSTOMER REVIEW AND APPROVAL IS REQUIRED IF SUPPLIED DATA REPORTS ANY CONDITION THAT DOES NOT MATCH "READ_ME.2" FILE PROVIDED.

TEST REQUIREMENTS: 100% NETLIST ELECTRICAL VERIFICATION USING CUSTOMER SUPPLIED IPC-D-356 NETLIST FOR OPENS AND SHORTS WHEN "GERBER DATA" IS PROVIDED. THIS VERIFICATION ALSO REQUIRED FOR "ODB+." DATA PER EMBEDDED NETLIST.

REQUIREMENTS:

- REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
- ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00115. (LATEST REVISION.)
- MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
- HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE A DIAMETER OF 0.005 INCHES FROM THEIR TRUE POSITION.
- PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 INCH BY CROSS SECTION.
- HOLE DIAMETERS APPLY AFTER PLATING.
- FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
- MINIMUM DESIGN LINE WIDTH IS .007 INCH.
- MINIMUM DESIGN SPACING IS .006 INCH.
- NON-FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE PERFORMED AFTER CUSTOMER APPROVAL.
- IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFR. MAY REQUEST APPROVAL TO TEAR DROP PADS TO MAINTAIN ANNULAR RING. (AT PAD TO TRACE INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)
- THIEVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM THE CUSTOMER:
 - A. THIEVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES, ALL OTHER FEATURES TO BE 0.200 INCH MINIMUM.
 - B. THERE SHALL BE NO THIEVING IN ANY AREAS FREE OF SOLDER MASK OR INTERNAL COPPER PLANES.
- MFR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED:
 - A. U.L. CODE-FLAMMABILITY RATING
 - B. DATE CODE (STAMP).
 - C. LOT NUMBER
 - D. MFR LOGO
 - E. SUCCESSFUL ELECTRICAL TEST.
- REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED.
- BOARDS TO BE SHIPPED IN ARRAY AND KEEP INTACT. PANEL TO BE SUBJECTED TO CUSTOMER'S APPROVAL. PANELED SOLDER PASTE STENCIL SHOULD BE SENT TO THE ADI.

6 LAYER STACKUP



IMPEDANCE TABLE

NOTE: ALL IMPEDANCE TOLERANCE +/-10%
SE = SINGLE ENDED
DP = DIFFERENTIAL PAIR

LAYER	IMPEDANCE	REFERENCE	LINE WIDTH	SPACE
L1	100 OHMS DP	L2	9.5MILS	6.5MILS
L1	50 OHMS SE	L2	7 MILS	N/A
L3	50 OHMS SE	L2	7 MILS	N/A
L6	50 OHMS SE	L5	7 MILS	N/A
L6	100 OHMS DP	L5	9.5MILS	6.5MILS

PRIMARY SIDE



SIZE	FSCM NO	DRAWING NUMBER	REV
C	24355	09-067221	E
SCALE	1/1	SHEET 2 OF 2	

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